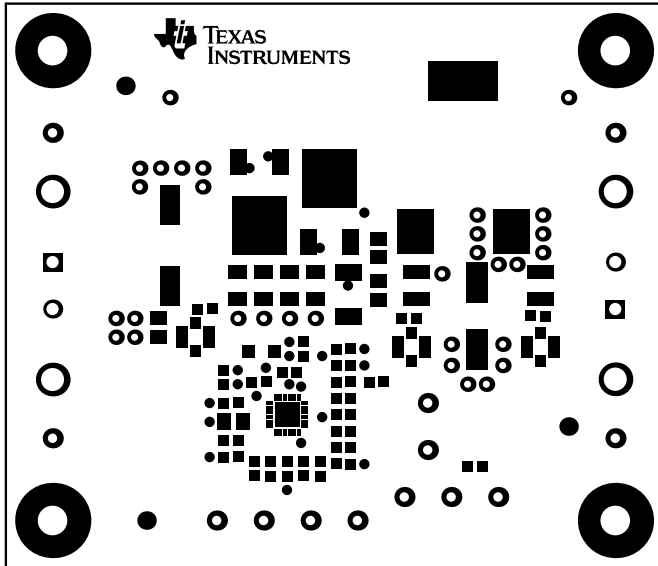
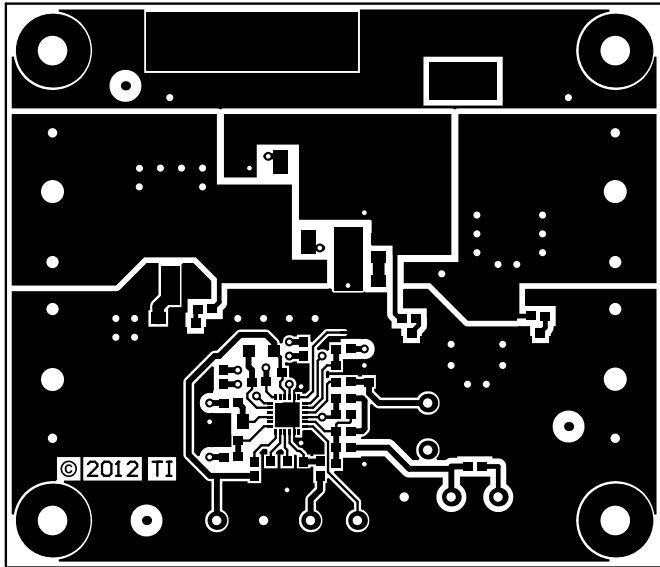


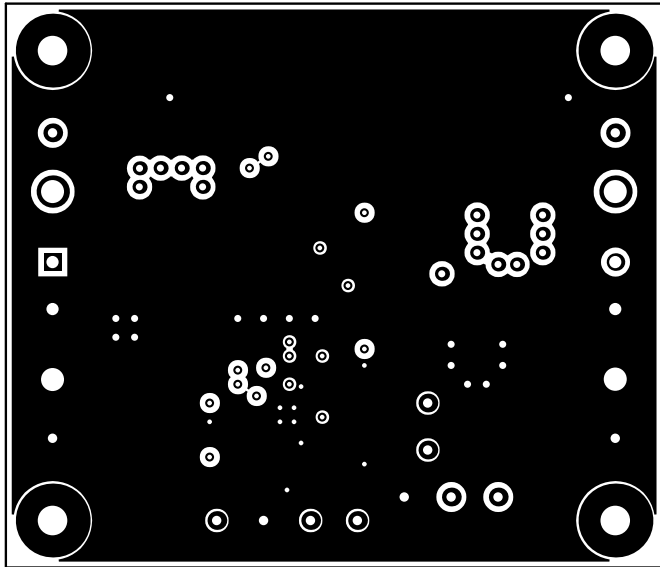
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP7872	REV: A	
LAYER NAME = Top Overlay			
PLOT NAME = Top Overlay	GENERATED : 10/4/2012 5:27:33 PM	TEXAS INSTRUMENTS	



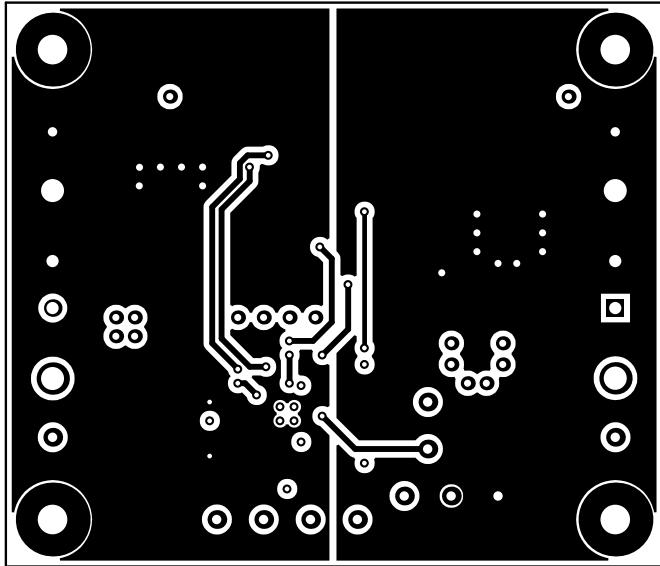
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP7872	REV: A	
LAYER NAME = Top Solder			
PLOT NAME = Top Solder Mask	GENERATED : 10/4/2012 5:27:34 PM	TEXAS INSTRUMENTS	



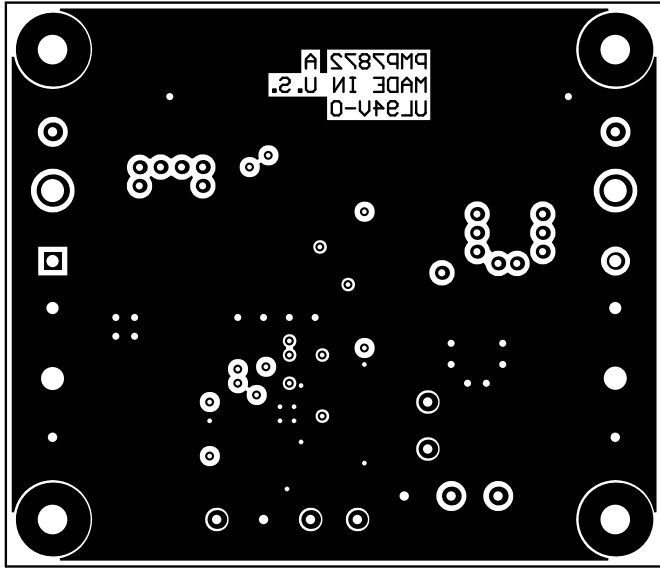
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP7872	REV: A	
LAYER NAME = Top Layer			
PLOT NAME = Top Layer	GENERATED : 10/4/2012 5:27:35 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP7872	REV: A	
LAYER NAME = MidLayer1			
PLOT NAME = Mid Layer 1	GENERATED : 10/4/2012 5:27:35 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP7872	REV: A	
LAYER NAME = MidLayer2			
PLOT NAME = Mid Layer 2	GENERATED : 10/4/2012 5:27:36 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE

BOARD #: PMP7872

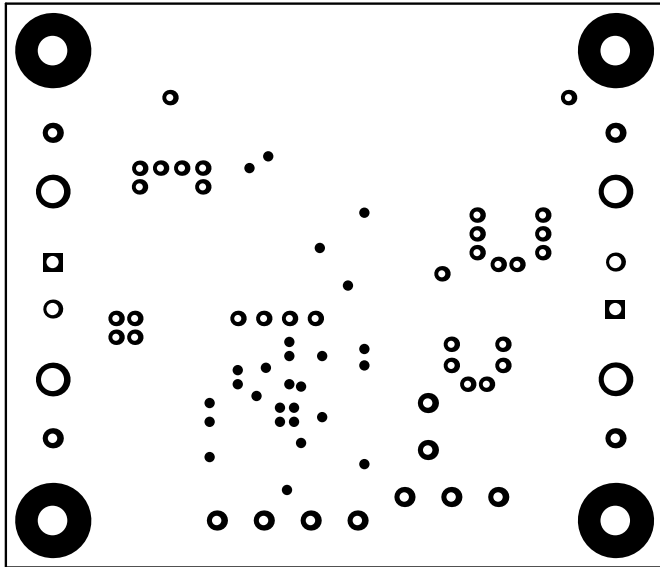
REV: A

LAYER NAME = Bottom Layer

PLOT NAME = Bottom Layer

GENERATED : 10/4/2012 5:27:36 PM

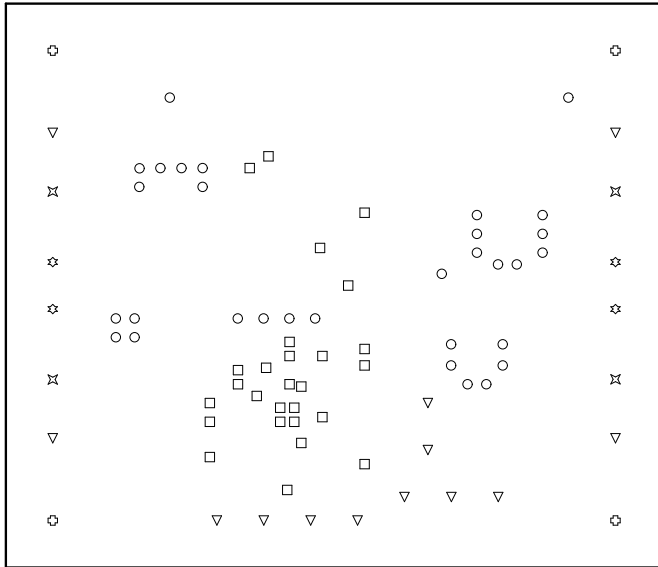
TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP7872	REV: A	
LAYER NAME = Bottom Solder			
PLOT NAME = Bottom Solder Mask	GENERATED : 10/4/2012 5:27:37 PM	TEXAS INSTRUMENTS	

██████ - 55859M9

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP7872	REV: A	
LAYER NAME = Bottom Overlay			
PLOT NAME = Bottom Overlay	GENERATED : 10/4/2012 5:27:37 PM	TEXAS INSTRUMENTS	



Symbol	Hit Count	Tool Size	Plated	Hole Type
□	27	20mil (0.508mm)	PTH	Round
○	31	30mil (0.762mm)	PTH	Round
▽	13	40mil (1.016mm)	PTH	Round
*	4	51.181mil (1.3mm)	PTH	Round
×	4	98.425mil (2.5mm)	PTH	Round
⊕	4	125.984mil (3.2mm)	PTH	Round
	83 Total			

Drill Table

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP7872	REV: A	
LAYER NAME = Drill Drawing			
PLOT NAME = Drill Drawing	GENERATED : 10/4/2012 5:27:38 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP7872	REV: A	
LAYER NAME = M2 Board Dimensions			
PLOT NAME = Board Dimensions	GENERATED : 10/4/2012 5:27:38 PM	TEXAS INSTRUMENTS	

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